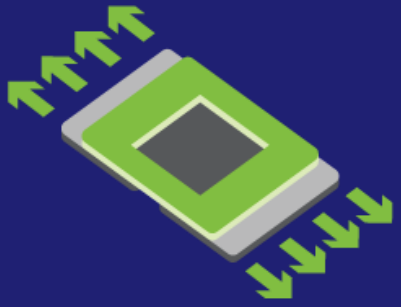




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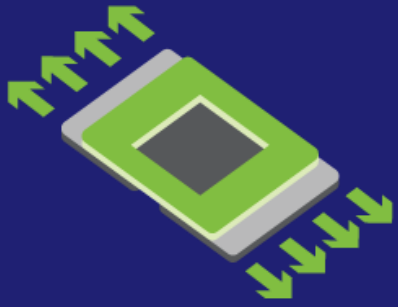


Open Accelerator Module Project (OAM)

is now the

Open Accelerator Infrastructure Project (OAI)

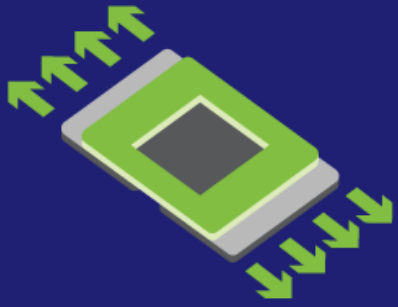




Open Accelerator Infrastructure

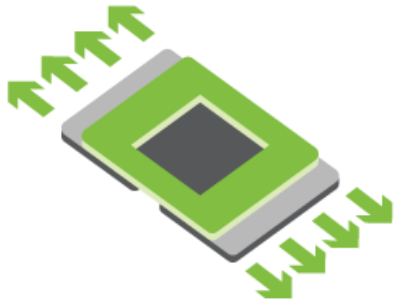
- OAI overall spec
- Universal Base Board (UBB)
- Host Interface Board (HIB)
- Power Distribution Board (PDB)
- OAM tray
- Security, Control, Management
- Chassis mechanical and cooling
- Expansion beyond Chassis



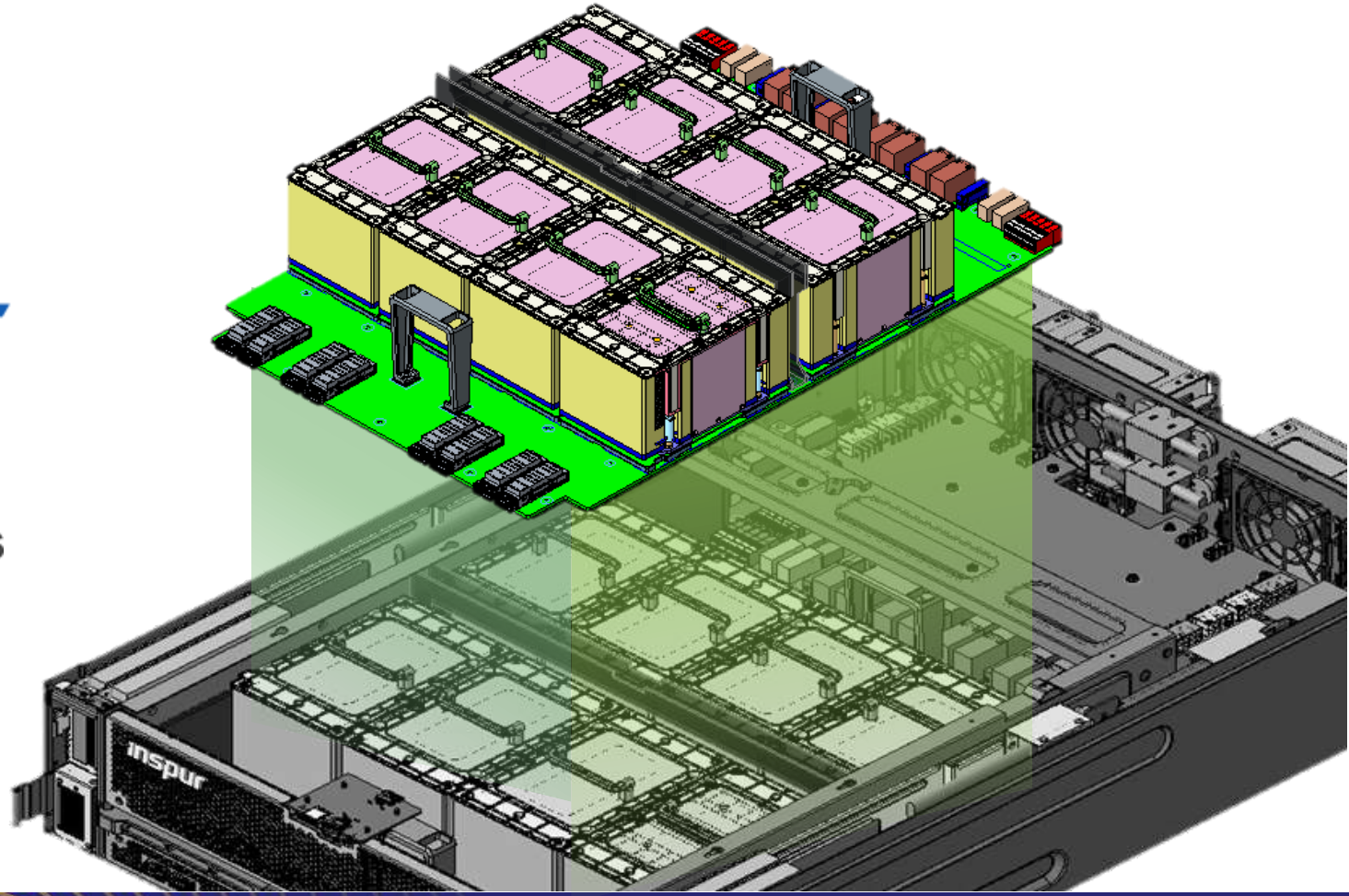


Open Accelerator Infrastructure

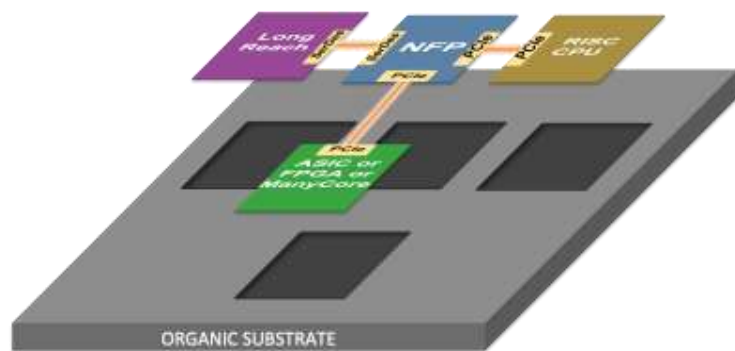
- Open Accelerator Module (OAM) spec released
- Universal Baseboard (UBB) spec in development
- Inspur showing first UBB today
- Prototype samples today at the Summit
- Inspur announces developer systems support



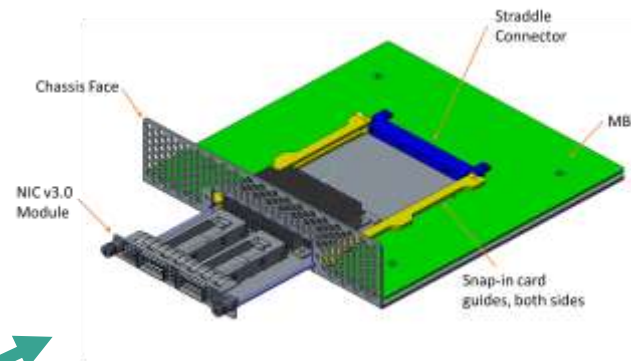
Universal Baseboard (UBB)



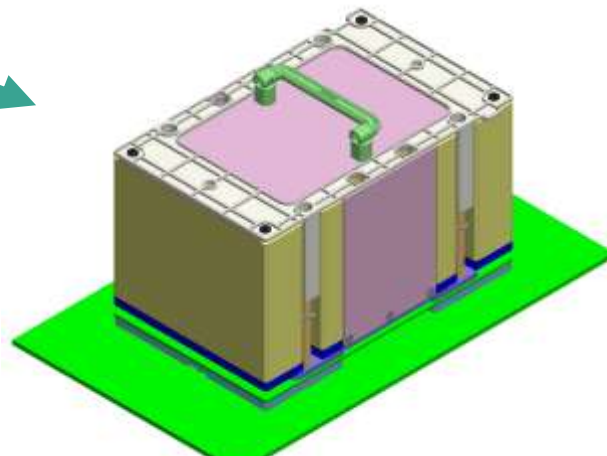
Chiplet Architecture



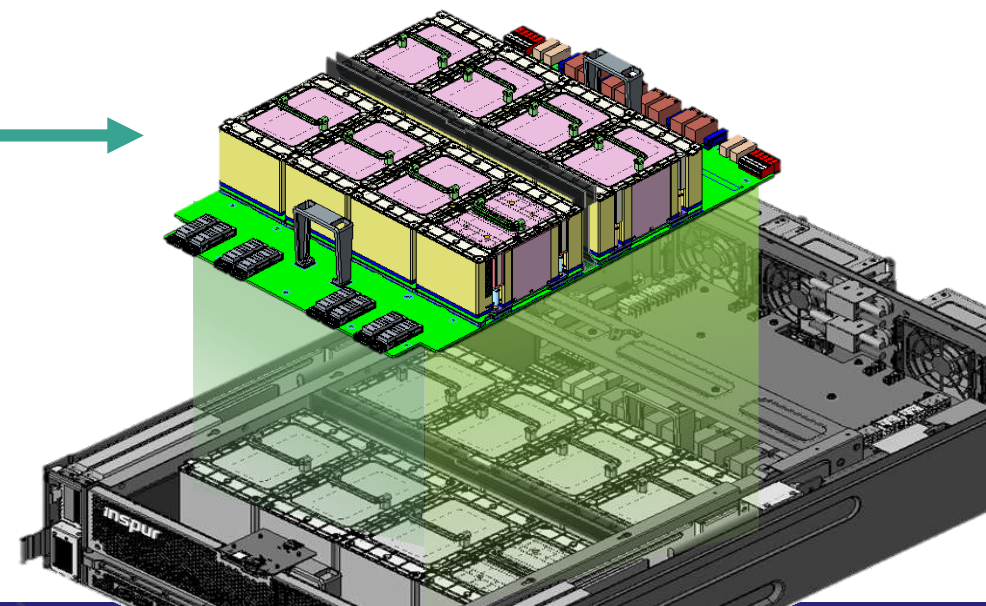
Mezzanine Architectures



Module Architecture



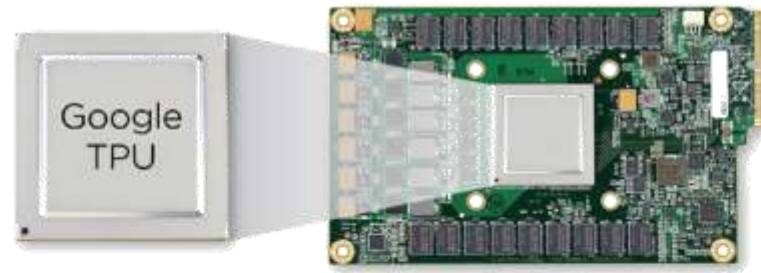
Systems Architectures



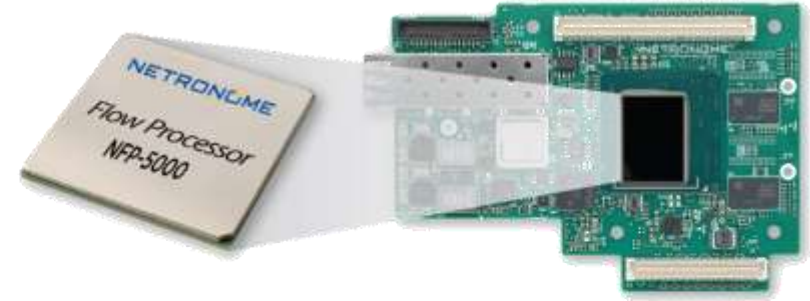
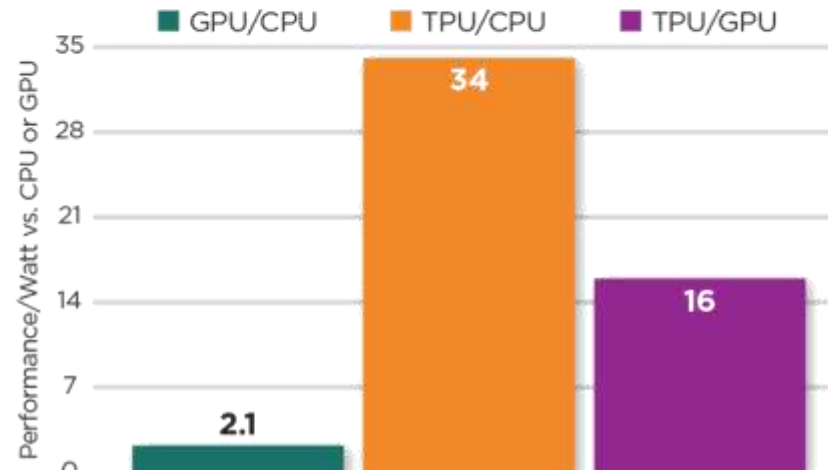


Open Domain-Specific Architecture Project

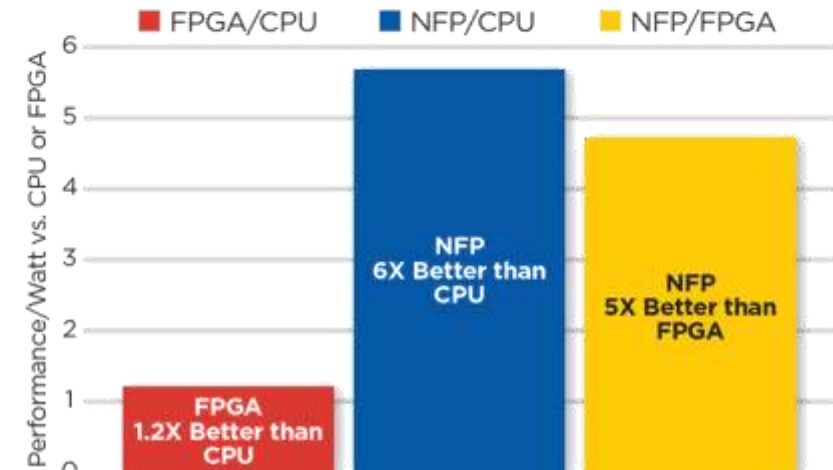
Significant
Performance
Advantages



Domain-Specific for Machine Learning and AI

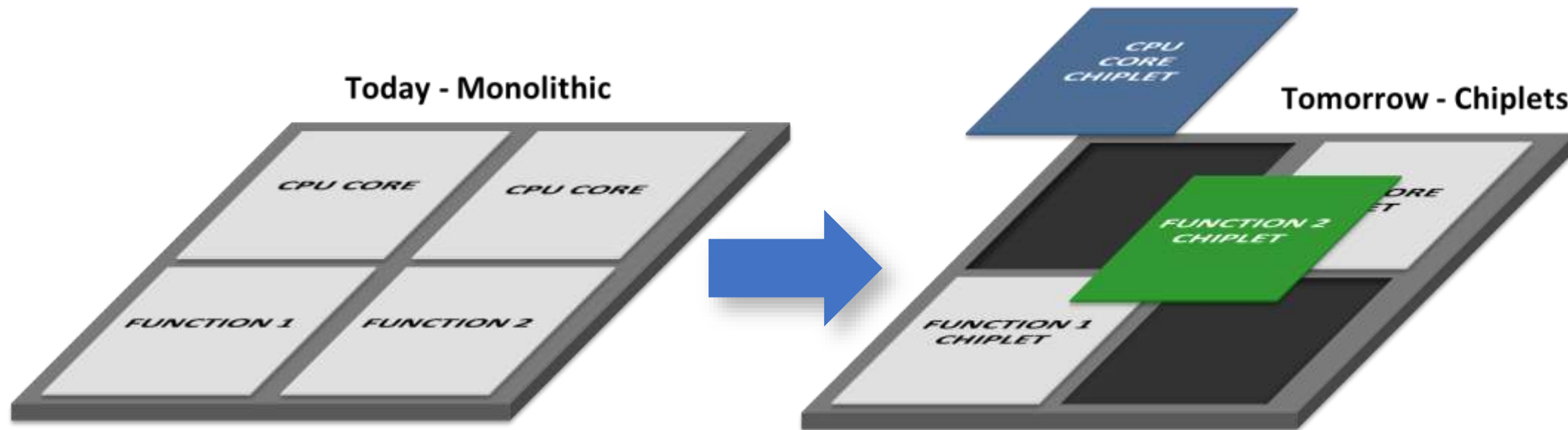


Domain-Specific for Networking and Security





Open Domain-Specific Architecture Project



Chiplets offer costs savings & heterogeneous integration options

*AMD Data



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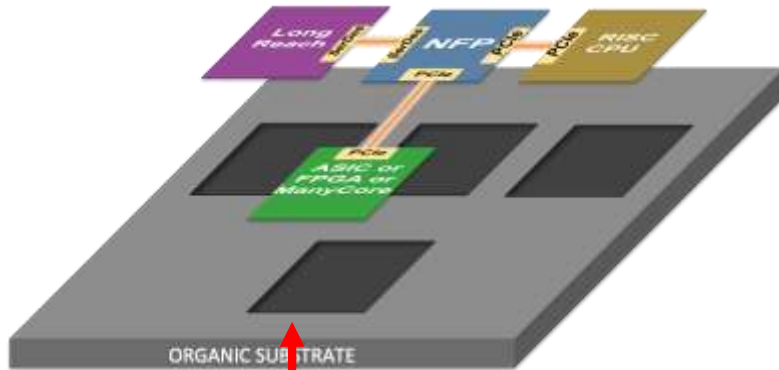
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ODSA Project Work Streams

PoC

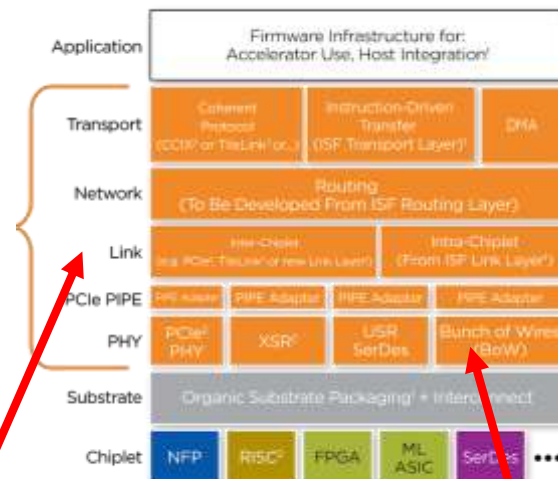
(Achronix/zGlue)



Develop
Packaging + Socket,
Dev Board

Interface/Standards

(AveraSemi, Facebook)

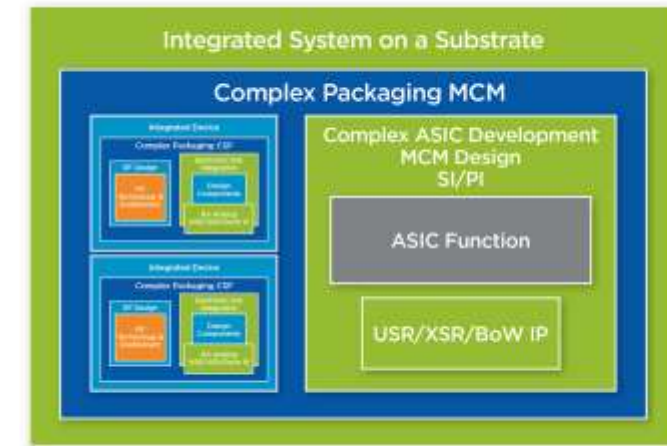


Define Architectural
Interface

Provide PHY technology

Business, IP and Workflow

(NXP, Kandou Bus)





Open Domain-Specific Architectures Project

- Chiplet Design Data Exchange being defined
- Bundle of Wires (BoW) interconnect paper released to WIKI
- BoW proof of concept milestone achieved today



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